

# Material Content Data Sheet

RoHS

| | | | |
|---|---|---|---|
| **Sales Product Name** | FF2000UXTR33T2M1 | **Revision** | 01 |
| **Issued** | 14.11.2024 | **Weight*** | 708 g |

| *Construction element* | *Material group* | *CAS-Nr. if applicable* | *Materials* | *Average mass** | *Sum* | *Traces* | *Comment* |
|---|---|---|---|---|---|---|---|
| semiconductors | inorganic material | 409-21-2 | silicon-carbide | 0,2% | 0,2% | | |
| | non noble metal | 7429-90-5 | aluminum | | | X | |
| | non noble metal | 7440-02-0 | nickel | | | X | |
| baseplate and substrate including metallisation | inorganic material | 409-21-2 | silicon-carbide | 14,5% | 37,2% | | |
| | non noble metal | 7429-90-5 | aluminum | 8,5% | | | |
| | non noble metal | 7440-50-8 | copper | 5,4% | | | |
| | inorganic material | 24304-00-5 | aluminium nitride | 4,3% | | | |
| | non noble metal | 7440-31-5 | tin | 2,4% | | | |
| | noble metal | 7440-22-4 | silver | 1,1% | | | |
| | non noble metal | 7440-02-0 | nickel | 0,7% | | | |
| | non noble metal | 7440-36-0 | antimony | 0,2% | | | |
| | inorganic material | 7723-14-0 | phosphorus | | | X | |
| bond wire | non noble metal | 7440-50-8 | copper | 1,4% | 1,4% | | |
| | non noble metal | 7429-90-5 | aluminum | | | X | |
| silicone compounds | polymers | - | silicone-rubber PVMQ | 10,1% | 10,3% | | |
| | inorganic material | - | other | 0,1% | | | no duty of declaration |
| | polymers | - | silicone-rubber VMQ | 0,1% | | | |
| housing and screws | polymers | - | polyamid | 13,3% | 22,1% | | |
| | inorganic material | - | glass fiber | 6,5% | | | |
| | inorganic material | - | flame retardant | 1,6% | | | no duty of declaration |
| | non noble metal | 7439-89-6 | iron | 0,4% | | | |
| | inorganic material | - | further additives | 0,1% | | | no duty of declaration |
| | organic material | 1333-86-4 | carbon black | 0,1% | | | |
| | non noble metal | 7440-02-0 | nickel | | | X | |
| | non noble metal | 7440-47-3 | chrome | | | X | |
| terminals | non noble metal | 7440-50-8 | copper | 21,5% | 28,6% | | |
| | non noble metal | 7439-89-6 | iron | 6,8% | | | |
| | non noble metal | 7440-31-5 | tin | 0,1% | | | |
| | non noble metal | 7440-02-0 | nickel | 0,1% | | X | |
| | non noble metal | 7440-66-6 | zinc | | | X | |
| | inorganic material | 7723-14-0 | phosphorus | | | X | |
| SMD components | non noble metal | 7439-89-6 | iron | | 0,011% | X | |
| | non noble metal | 7440-02-0 | nickel | | | X | |
| | inorganic material | 1317-36-8 | lead monoxide | 0,002% | | | RoHS compliant; according to exception 7c. I |
| | non noble metal | 7440-50-8 | copper | | | X | |
| | non noble metal | 7440-31-5 | tin | | | X | |
| *deviation | < 25% | | | Sum in total: | 100% | | |

***Important Remarks:***

1. This document provides full declaration of all materials present in Infineon products above a threshold of 0,1 % b.w. (1000 ppm).
2. Trace concentrations (i.e. < 0,1 % b.w) present in products are marked with an "X" as far as they represent substances-of-concern.
   A list of substances-of-concern can be found at http://www.infineon.com/soc.
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